

Title (en)
METHOD FOR OBTAINING A DEPOSIT OF A YELLOW GOLD ALLOY BY GALVANOPLASTY WITHOUT USING TOXIC METALS

Title (de)
VERFAHREN ZUM ERHALTEN EINER GELBEN GOLDLEGIERUNGSABLAGERUNG DURCH GALVANOPLASTIK OHNE VERWENDUNG VON GIFTIGEN METALLEN

Title (fr)
PROCÉDÉ D'OBTENTION D'UN DÉPÔT D'ALLIAGE D'OR JAUNE PAR GALVANOPLASTIE SANS UTILISATION DE MÉTAUX TOXIQUES

Publication
EP 2312021 B1 20200318 (FR)

Application
EP 09173198 A 20091015

Priority
EP 09173198 A 20091015

Abstract (en)
[origin: EP2312021A1] Galvanoplastic deposition of a gold alloy on an electrode dipped into a bath including gold metal in alkaline aurocyanide form, organometallic compounds, a wetting agent, a sequestering agent and free cyanide, where the alloy metal is copper, which is in double copper and potassium cyanide form, and silver, or in cyanide form, comprises depositing a mirror-bright yellow gold alloy on the electrode, where the bath respects a proportion of 9.08% gold, 90.85% copper and 0.07% silver containing neither cadmium nor zinc. Independent claims are also included for: (1) an electrolytic deposition in the form of a gold alloy obtained from the above method having a thickness of 1-800 mu and comprising copper and silver as the third main compound, allowing a bright 3N color to be obtained; and (2) an electrolytic deposition is in the form of a gold, copper, and silver alloy, where the deposition is made of gold (75%), copper (21%) and silver (4%), allowing a bright 3N color to be obtained.

IPC 8 full level
C25D 3/62 (2006.01)

CPC (source: EP US)
C25D 3/62 (2013.01 - EP US); **B05D 1/18** (2013.01 - US); **C25D 3/56** (2013.01 - US); **C25D 3/58** (2013.01 - US); **C25D 7/005** (2013.01 - US)

Cited by
EP2505691A1; US10053789B2; US10793961B2

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